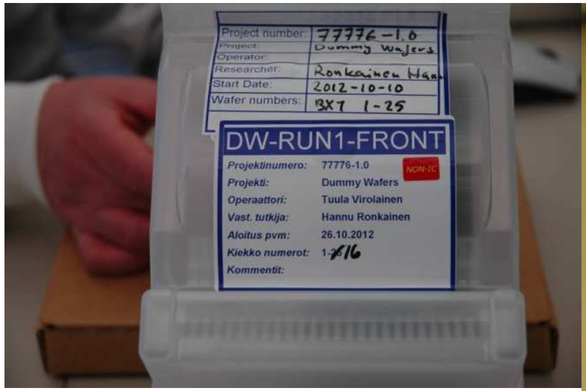
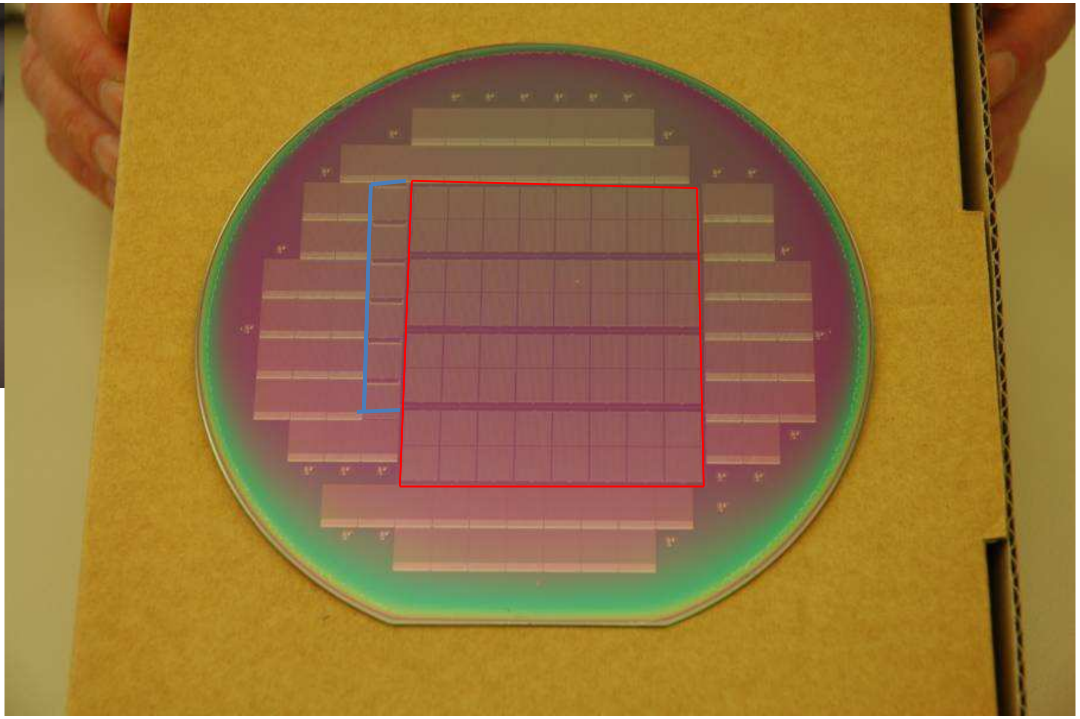
VTT delivered 26 dummy wafers

PICTURES



Project number: 77776-1.0
Project: Dummy Wafers
Operator:
Researcher: Ronkainen Han
Start Date: 2012-10-10
Wafer numbers: BX7 1-25

DW-RUN1-FRONT
Projektinumero: 77776-1.0
Projekti: Dummy Wafers
Operaattori: Tuula Virolainen
Vast. tutkija: Hannu Ronkainen
Aloitus pvm: 26.10.2012
Kiekko numerot: 1-~~2~~16
Kommentit:



No UBM
No Bumps

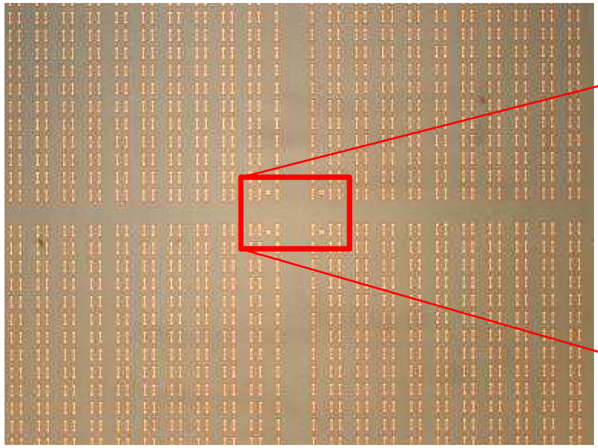
Setup wafers for the 15 µm ENEPIG process at Pac Tech

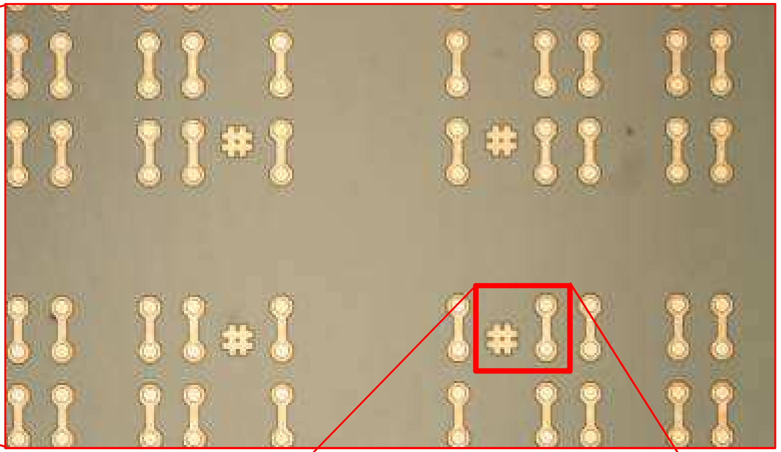
Dummy structures with daisy chain pattern

- 4 sensors
- 6 single sensors
- 70 ROC

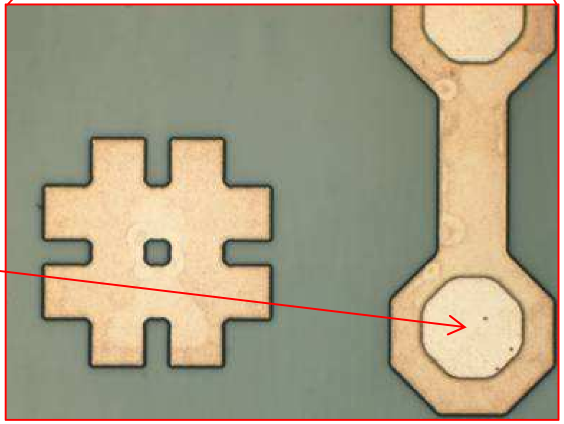
Sensors have daisy chain structure with 30 µm opening

MICROSCOPE PICTURES



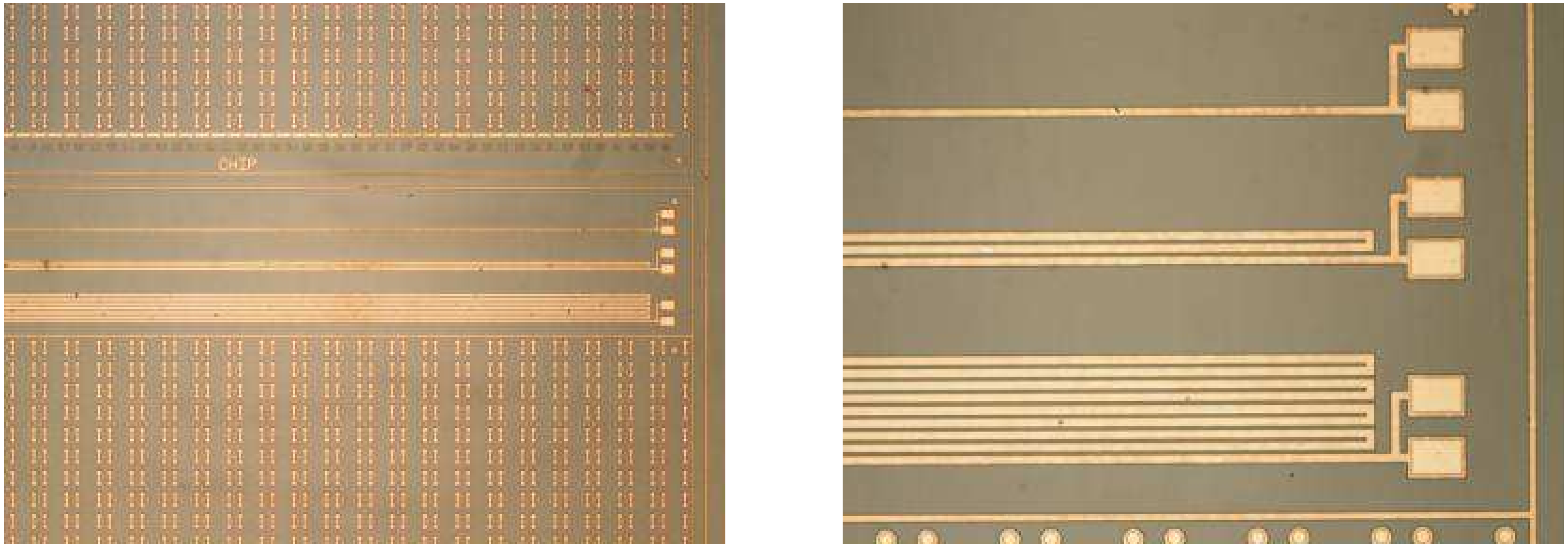


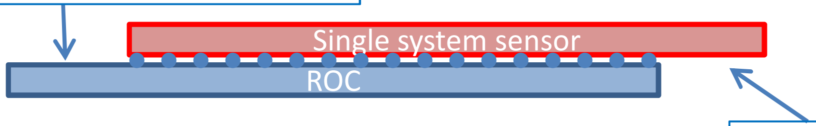
1.2 µm AlSiCu
50 µm pad size
30 µm passivation opening



Single sensors resemble sensor structure but provide also resistance test structures

MICROSCOPE PICTURES



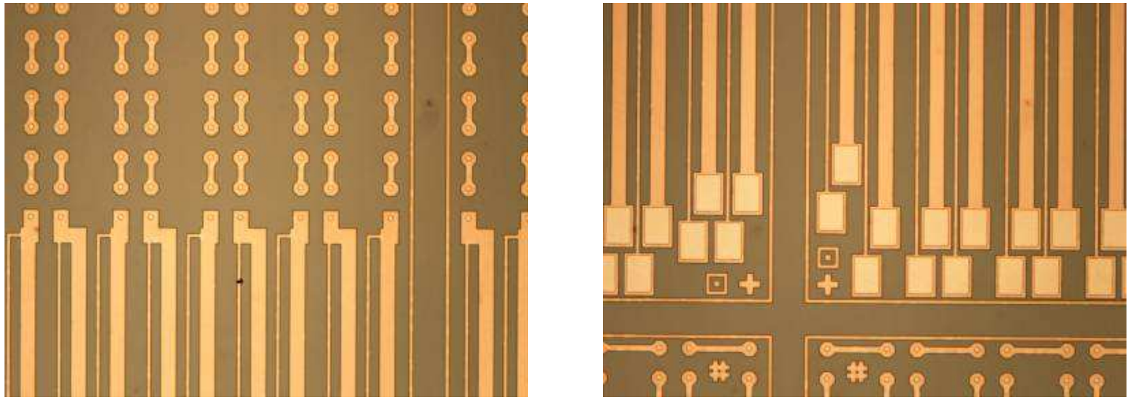


Pads for electrical contact

Area for test structures

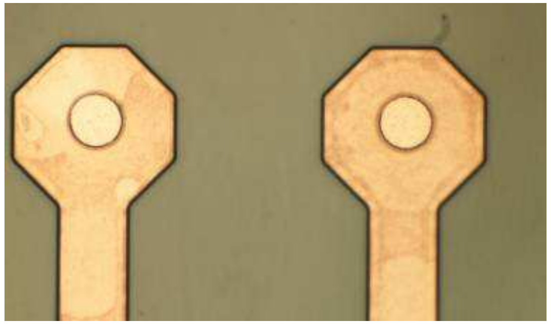
ROCs have daisy chain structure with 15 µm opening

MICROSCOPE PICTURES

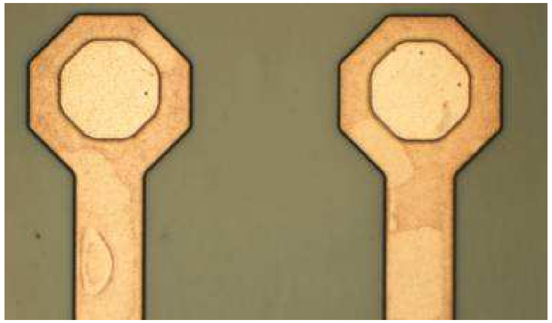


Daisy chain structure and pads for four-probe-resistance measures

ROC side:
15 µm
passivation
opening



Sensor side:
30 µm
passivation
opening



Plans

15 of the 26 wafers are dedicateed for ENEPIG setup
starting in February (up to 6 weeks)

Residual 11+ wafers for DESY production tests

Next week telephone meeting with Pac Tech for further planing
analogROC wafer
5+1 CiS sensor wafer
50 CiS sensor wafers